

Features & Benefits

- * Mechanical compatibility with direct mounting of the COB products to the LED thermal body and thermal performance matching the lumen packages.
- * For Down light designs from 3200 to 4500 lumen.
- * Thermal resistance range R_{th} 1.21°C/W.
- * Full accessory kit with LED cooler Body, PSU mounting shrapnel & lens holder.
- * Other accessories like COB holder & lens separate available.
- * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's.
- * Forged from highly conductive aluminum (ADC12) .
- * Dimension 160×160mm - Standard height 165 mm , Other heights on request.
- * 3 standard colors - white powder,black powder and gray powder.



Cover



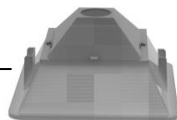
Heatsink



Holder



PC Reflector



- 01) Bridelux: Vero 10/13 Vero SE 10/13 LED engines;
- 02) Cree: XLamp CXA 13xx, XLamp CXB 15xx, CXA 18xx Series engines;
- 03) Citizen: CLU026,CLU027,CLU028,CLU036,CLU038,CLU721,CLU711, CLU701 LED engines;
- 04) Edison: EdiLex III COB LED engines;
- 05) GE lighting: Infusion™ LED engines;
- 06) LG Innotek: 7W, 10W, 16W, 21W, 32W LED engines;
- 07) LumiLEDs: LUXEON 1202/1203/1204/1205/1208 LED engines;
- 08) Lumens: Ergon-COB 15xx, 18xx LED engines;
- 09) Luminus: CXM-6, CHM/CLM/CXM-9/14/18 LED engines;
- 10) Nichia: NVxxx024Z,NVxxx036Z, NFCWxxxB Series LED engines;
- 11) Osram: SOLERIQ® S 9/S13, Z6 Mini LED engines;
- 12) Philips: Fortimo SLM LED engines;
- 13) Prolight Opto: PACJ-7xxx/14xxx/21xxx/28xxx-xxxx, PACK-35xxx/42xxx/57xxx-xxxx engines;
- 14) Samsung: LCxxxC Series, LCxxxD Series LED engines;
- 15) Seoul Semiconductor:SAWxxxxxx Series, DC COB LED engines;
- 16) Tridonic: SLE G5, SLE G6 10/15/17mm LED engines;
- 17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;

Order Information

Example: Cube-165-WH

Cube - **1** - **2**



Product model

- 165



Finish

- WH White

- BK Black

- GY Gray

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



The product data table

	 <i>Cube</i>
Model No.	Cube-165
Heatsink Size	160x160x165 mm
Heatsink Material	ADC12
Heatsink Finish	White/Black/Gray
Weight	1755g
Dissipated power (Ths-amb,50°C)	40 (W)
Beam Angle	50°
Thermal Resistance (Rhs-amb)	1.21(°C/W)

* 3D files are available in ParaSolid, STP and IGS on request

* The thermal resistance R_{th} is determined with a calibrated heat source of 18mm×18mm central placed on the heat sink, T_{amb} 40° and an open environment. Reference data @ heat sink to ambient temperature rise T_{hs-amb} 50°C

The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power P_d

* Dissipated power P_d . Reference data @ heat sink to ambient temperature rise T_{hs-amb} 50°C

The maximal dissipated power needs to be verified in function of required case temperature T_c or junction temperature T_j and related to the estimated ambient temperature where the light fixture will be placed
Please be aware the dissipated power P_d is not the same as the electrical power P_e of a LED module

To calculate the dissipated power please use the following formula: $P_d = P_e \times (1-\eta_L)$

P_d - Dissipated power

P_e - Electrical power

η_L = Light efficiency of the LED module

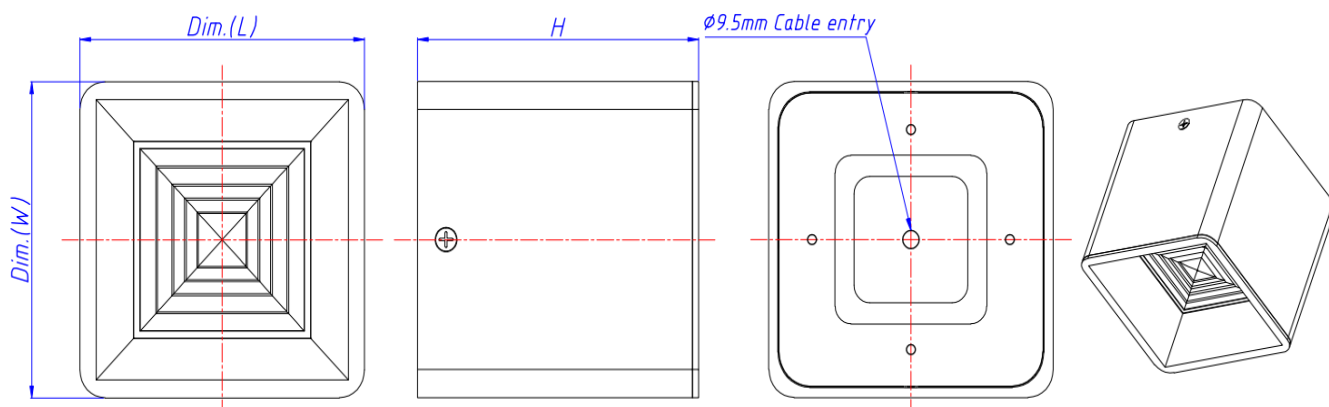


Cube

Cube-165 Lighting Kits assembly & introduction

Drawings & Type Selection

Type	Dim.(mm)	Height(mm)	Power(w)	LES(mm)	Beam Angle	Cut-out(mm)
Cube-165	160×160	165	40	17	50°	N/A



Components introduction

1. Remove the reflector, Install the COB

2. Fix the COB by the holder and screw



3. Vertically align the shrapnel and press down on the reflector assembly

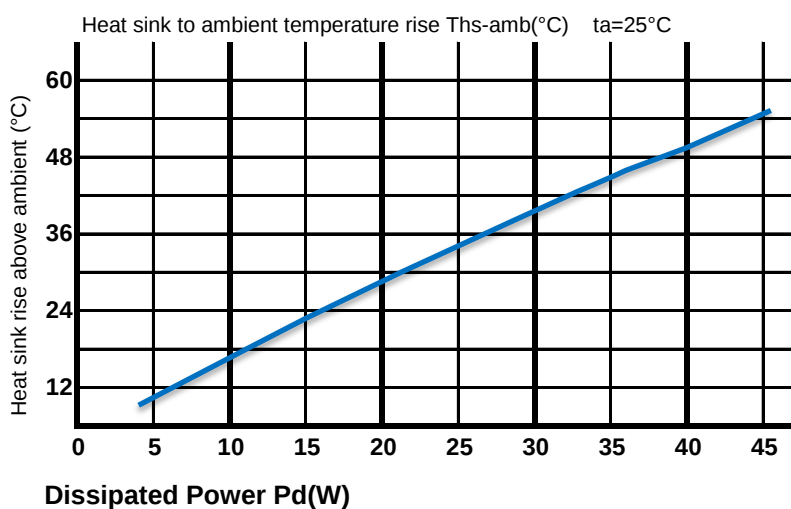


Cube

Cube-165 Lighting Kits assembly & introduction

The thermal data table

Dissipated Power Pd(W)	Pd=Pe x (1-ηL)	Heat sink to ambient thermal resistance Rhs-amb(°C/W)	Heat sink to ambient temperature rise Ths-amb(°C)
		Cube-165	
5		1.46	7.4
15		1.41	21.5
20		1.38	28
30		1.28	39
35		1.24	44
40		1.21	49
45		1.18	54



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

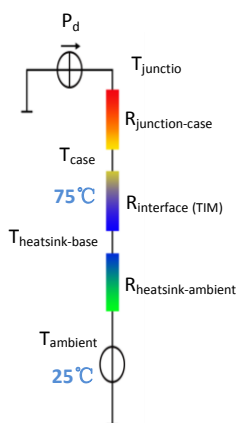
*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta) / Pd$

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package $R_{\text{interface (TIM)}}$ and $R_{\text{heatsink-ambient}}$ can be integrated into the thermal resistance $R_{\text{case-ambient}}$ at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot Pd + T_{\text{ambient}}$$